#### **Features**

- Fast Read Access Time 120 ns
- Fast Byte Write 200 µs or 1 ms
- Self-timed Byte Write Cycle
  - Internal Address and Data Latches
  - Internal Control Timer
  - Automatic Clear Before Write
- Direct Microprocessor Control
  - READY/BUSY Open Drain Output
  - DATA Polling
- Low Power
  - 30 mA Active Current
  - 100 µA CMOS Standby Current
- High Reliability
  - Endurance: 10<sup>4</sup> or 10<sup>5</sup> Cycles
  - Data Retention: 10 Years
- 5V ± 10% Supply
- CMOS and TTL Compatible Inputs and Outputs
- JEDEC Approved Byte-wide Pinout
- Commercial and Industrial Temperature Ranges

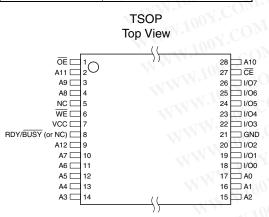
#### **Description**

The AT28C64 is a low-power, high-performance 8,192 words by 8-bit nonvolatile electrically erasable and programmable read only memory with popular, easy-to-use features. The device is manufactured with Atmel's reliable nonvolatile technology.

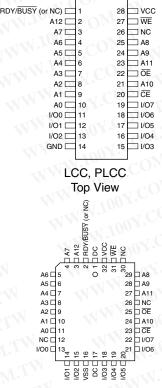
(continued)

#### **Pin Configurations**

Pin Name	Function
A0 - A12	Addresses
CE	Chip Enable
ŌĒ	Output Enable
WE	Write Enable
I/O0 - I/O7	Data Inputs/Outputs
RDY/BUSY	Ready/Busy Output
NC	No Connect
DC	Don't Connect







Note: PLCC package pins 1 and 17 are DON'T CONNECT.





# 64K (8K x 8) Parallel EEPROMs

## AT28C64 AT28C64X

勝 特 力 材 料 886-3-5753170 胜特力电子(上海) 86-21-54151736 胜特力电子(深圳) 86-755-83298787 Http://www.100y.com.tw

Rev. 0001H-12/99



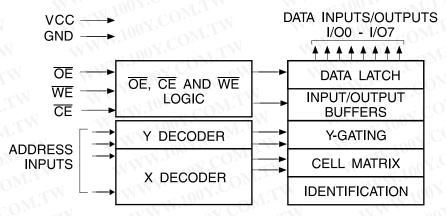
The AT28C64 is accessed like a Static RAM for the read or write cycles without the need for external components. During a byte write, the address and data are latched internally, freeing the microprocessor address and data bus for other operations. Following the initiation of a write cycle, the device will go to a busy state and automatically clear and write the latched data using an internal control timer. The device includes two methods for detecting the end of a write cycle, level detection of RDY/BUSY (unless pin 1 is N.C.) and DATA Polling of I/O<sub>7</sub>. Once the end of a write

cycle has been detected, a new access for a read or write can begin.

The CMOS technology offers fast access times of 120 ns at low power dissipation. When the chip is deselected the standby current is less than 100  $\mu$ A.

Atmel's AT28C64 has additional features to ensure high quality and manufacturability. The device utilizes error correction internally for extended endurance and for improved data retention characteristics. An extra 32 bytes of EEPROM are available for device identification or tracking.

#### **Block Diagram**



#### **Absolute Maximum Ratings\***

Temperature under Bias	55°C to +125°C
Storage Temperature	65°C to +150°C
All Input Voltages (including NC Pins) with Respect to Ground	0.6V to +6.25V
All Output Voltages with Respect to Ground	0.6V to V <sub>CC</sub> + 0.6V
Voltage on $\overline{\text{OE}}$ and A9 with Respect to Ground	0.6V to +13.5V

\*NOTICE:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability

## Device Operation

**READ:** The AT28C64 is accessed like a Static RAM. When  $\overline{CE}$  and  $\overline{OE}$  are low and  $\overline{WE}$  is high, the data stored at the memory location determined by the address pins is asserted on the outputs. The outputs are put in a high impedance state whenever  $\overline{CE}$  or  $\overline{OE}$  is high. This dual line control gives designers increased flexibility in preventing bus contention.

**BYTE WRITE:** Writing data into the AT28C64 is similar to writing into a Static RAM. A low pulse on the  $\overline{WE}$  or  $\overline{CE}$  input with  $\overline{OE}$  high and  $\overline{CE}$  or  $\overline{WE}$  low (respectively) initiates a byte write. The address location is latched on the falling edge of  $\overline{WE}$  (or  $\overline{CE}$ ); the new data is latched on the rising edge. Internally, the device performs a self-clear before write. Once a byte write has been started, it will automatically time itself to completion. Once a programming operation has been initiated and for the duration of  $t_{WC}$ , a read operation will effectively be a polling operation.

**FAST BYTE WRITE:** The AT28C64E offers a byte write time of 200 µs maximum. This feature allows the entire device to be rewritten in 1.6 seconds.

**READY/BUSY:** Pin 1 is an open drain RDY/BUSY output that can be used to detect the end of a write cycle. RDY/BUSY is actively pulled low during the write cycle and is released at the completion of the write. The open drain connection allows for OR-tying of several devices to the

same RDY/BUSY line. The RDY/BUSY pin is not connected for the AT28C64X.

**DATA POLLING:** The AT28C64 provides DATA Polling to signal the completion of a write cycle. During a write cycle, an attempted read of the data being written results in the complement of that data for I/O<sub>7</sub> (the other outputs are indeterminate). When the write cycle is finished, true data appears on all outputs.

**WRITE PROTECTION:** Inadvertent writes to the device are protected against in the following ways: (a)  $V_{CC}$  sense – if  $V_{CC}$  is below 3.8V (typical) the write function is inhibited; (b)  $V_{CC}$  power on delay – once  $V_{CC}$  has reached 3.8V the device will automatically time out 5 ms (typical) before allowing a byte write; and (c) write inhibit – holding any one of  $\overline{OE}$  low,  $\overline{CE}$  high or  $\overline{WE}$  high inhibits byte write cycles.

**CHIP CLEAR:** The contents of the entire memory of the AT28C64 may be set to the high state by the CHIP CLEAR operation. By setting  $\overline{CE}$  low and  $\overline{OE}$  to 12 volts, the chip is cleared when a 10 msec low pulse is applied to  $\overline{WE}$ .

**DEVICE IDENTIFICATION:** An extra 32 bytes of EEPROM memory are available to the user for device identification. By raising A9 to  $12\pm0.5V$  and using address locations 1FE0H to 1FFFH the additional bytes may be written to or read from in the same manner as the regular memory array.





### DC and AC Operating Range

DC and AC Ope	erating Ra	nge	WWW.100Y.CC	OM.TW		
TOMITWO	W 100	AT28C64-12	AT28C64-15	AT28C64-20	AT28C64-25	
Operating	Com.	0°C - 70°C	0°C - 70°C	0°C - 70°C	0°C - 70°C	
Temperature (Case)	Ind.	-40°C - 85°C	-40°C - 85°C	-40°C - 85°C	-40°C - 85°C	
V <sub>CC</sub> Power Supply	MM	5V ± 10%	5V ± 10%	5V ± 10%	5V ± 10%	

#### **Operating Modes**

Mode CV WWW	CE	ŌE	WE	I/O
Read	V <sub>IL</sub>	V <sub>IL</sub>	V <sub>IH</sub>	D <sub>OUT</sub>
Write <sup>(2)</sup>	V <sub>IL</sub>	V <sub>IH</sub>	V <sub>IL</sub>	D <sub>IN</sub>
Standby/Write Inhibit	V <sub>IH</sub>	X <sup>(1)</sup>	100X-X	High Z
Write Inhibit	X,COM	X WWW	V <sub>IH</sub>	IW
Write Inhibit	X X CO	V <sub>IL</sub>	X.CO	WI
Output Disable	X X C	V <sub>IH</sub>	X CON	High Z
Chip Erase	V <sub>IL</sub>	V <sub>H</sub> (3)	V <sub>IL</sub> CO	High Z

#### **DC Characteristics**

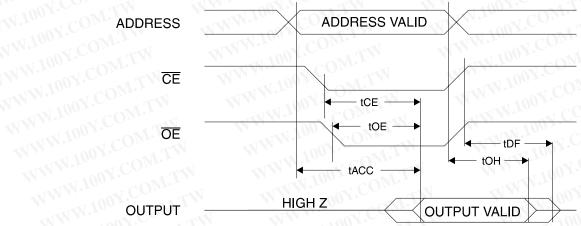
Symbol	Parameter	Condition	Condition		Max	Units
l <sub>Li</sub>	Input Load Current	$V_{IN} = 0V \text{ to } V_{CC} + 1V$			10 CO	μΑ
I <sub>LO</sub>	Output Leakage Current	$V_{I/O} = 0V \text{ to } V_{CC}$			10	μA
I <sub>SB1</sub>	V <sub>CC</sub> Standby Current CMOS	$\overline{\text{CE}} = \text{V}_{\text{CC}} - 0.3 \text{V to V}_{\text{CC}} + 1.0 \text{V}$			100	μА
	V Ctandby Current TT	CF 2.0V to V . 1.0V	Com.	1	2003	mA
I <sub>SB2</sub>	V <sub>CC</sub> Standby Current TTL	$\overline{\text{CE}}$ = 2.0V to V <sub>CC</sub> + 1.0V	Ind.		3.100	mA
	V <sub>CC</sub> Active Current AC	$\frac{f = 5 \text{ MHz; I}_{OUT} = 0 \text{ mA}}{\overline{CE} = V_{IL}}$	Com.		30	mA
cc \ \rangle \( \mathbf{v}_0 \)			Ind.	I.TW	45	mA
V <sub>IL</sub>	Input Low Voltage	TIM WWW.100X.CO		M.T.W	0.8	00 V
V <sub>IH</sub>	Input High Voltage	WITH WITH	N 100Y.C	2.0	N W	100 V
V <sub>OL</sub>	Output Low Voltage	I <sub>OL</sub> = 2.1 mA = 4.0 mA for RDY/BUSY	VVV.100Y.C	OM.TW	0.45	1.100 V
V <sub>OH</sub>	Output High Voltage	I <sub>OH</sub> = -400 μA	MMITO	2.4	WW	V

Http://www. 100y. com. tw

#### **AC Read Characteristics**

CON.TH WILLIAMS		AT28C64-12		AT28C64-15		AT28C64-20		AT28C64-25		
Symbol	Parameter	Min	Max	Min	Max	Min	Max	Min	Max	Units
t <sub>ACC</sub>	Address to Output Delay	M.T.	120	11/11	150		200		250	ns
t <sub>CE</sub> <sup>(1)</sup>	CE to Output Delay	T.Mo.	120		150	7.00	200		250	ns
t <sub>OE</sub> <sup>(2)</sup>	OE to Output Delay	10	60	10	70	10	80	10	100	ns
t <sub>DF</sub> <sup>(3)(4)</sup>	CE or OE High to Output Float	0	45	0	50	000.	55	0	60	ns
t <sub>OH</sub>	Output Hold from $\overline{OE}$ , $\overline{CE}$ or Address, whichever occurred first	0	I.TW	0	NW	0	COM.	0		ns

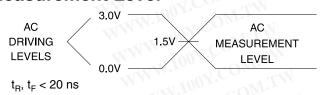
## AC Read Waveforms<sup>(1)(2)(3)(4)</sup>



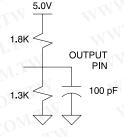
1.  $\overline{CE}$  may be delayed up to  $t_{ACC}$  -  $t_{CE}$  after the address transition without impact on  $t_{ACC}$ .

- 2.  $\overline{\text{OE}}$  may be delayed up to  $t_{\text{CE}}$   $t_{\text{OE}}$  after the falling edge of  $\overline{\text{CE}}$  without impact on  $t_{\text{CE}}$  or by  $t_{\text{ACC}}$   $t_{\text{OE}}$  after an address change without impact on tACC.
- 3.  $t_{DF}$  is specified from  $\overline{OE}$  or  $\overline{CE}$  whichever occurs first ( $C_L = 5 \text{ pF}$ ).
- 4. This parameter is characterized and is not 100% tested.

#### **Input Test Waveforms and Measurement Level**



## **Output Test Load**



#### **Pin Capacitance**

Symbol	Тур	Max	Units	Conditions
C <sub>IN</sub>	4	1003.	pF COM	$V_{IN} = 0V$
C <sub>OUT</sub>	8	12	pF	$V_{OUT} = 0V$



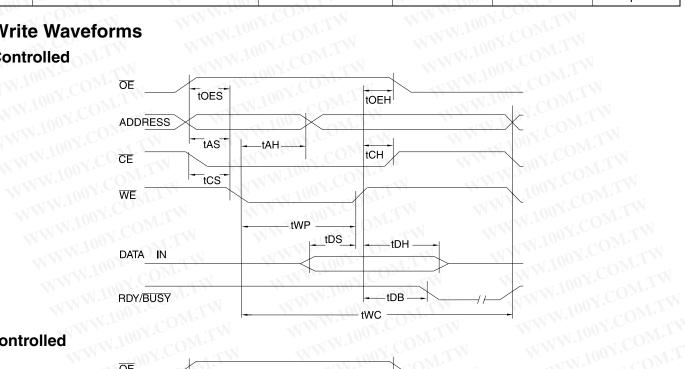


勝 特 力 材 料 886-3-5753170 胜特力电子(上海) 86-21-54151736 胜特力电子(深圳) 86-755-83298787

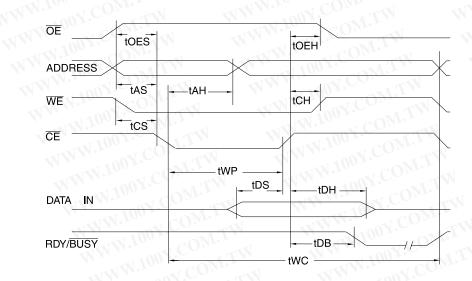
Symbol	Parameter	A A A	Min	Max	Unit
t <sub>AS</sub> , t <sub>OES</sub>	Address, OE Setup Time		10	~1	ns
t <sub>AH</sub>	Address Hold Time		50	N	ns
t <sub>WP</sub>	Write Pulse Width (WE or CE)		100	1000	ns
t <sub>DS</sub>	Data Setup Time		50	TW	ns
t <sub>DH</sub> , t <sub>OEH</sub>	Data, <del>OE</del> Hold Time	Data, OE Hold Time		V.TW	ns
t <sub>CS</sub> , t <sub>CH</sub>	CE to WE and WE to CE Setup and Ho	old Time	007.00	M.TW	ns
t <sub>DB</sub>	Time to Device Busy	.COMITW	VI W 100 Y.C.	50	ns
N.IOOY	Write Cycle Time (entire available)	AT28C64	MM 100X.	WE.MO	ms
t <sub>WC</sub>	Write Cycle Time (option available)	AT28C64E	MAM	200	μs

#### **AC Write Waveforms**

#### **WE** Controlled



#### **CE** Controlled



## Data Polling Characteristics<sup>(1)</sup>

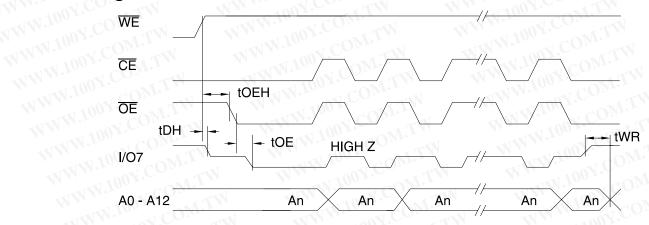
Data Polling Characteristics <sup>(1)</sup>								
Symbol	Parameter	Min M	Тур	Max	Units			
t <sub>DH</sub>	Data Hold Time	10	UIM		ns			
t <sub>OEH</sub>	OE Hold Time	100 10	M.TW		ns			
t <sub>OE</sub>	OE to Output Delay <sup>(2)</sup>	VV 100X.	M.TW		ns			
t <sub>WR</sub>	Write Recovery Time	10	OM.TW		ns			

WWW.100Y.COM.

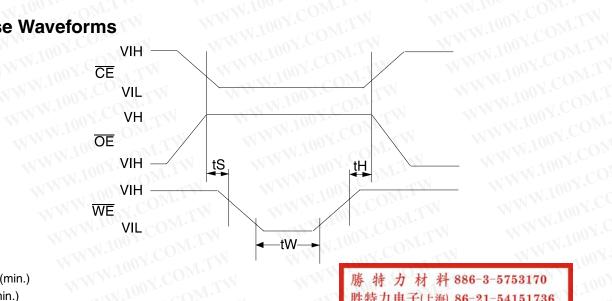
Notes: 1. These parameters are characterized and not 100% tested.

2. See "AC Read Characteristics".

#### **Data** Polling Waveforms



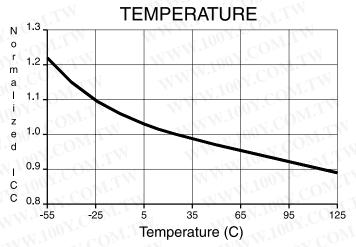
#### **Chip Erase Waveforms**



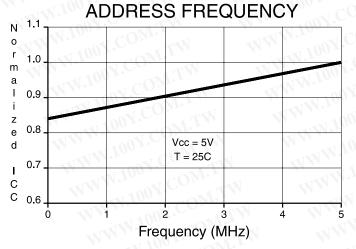
 $t_S = t_H = 1 \mu sec (min.)$  $t_W = 10 \text{ msec (min.)}$  $V_H = 12.0 \pm 0.5 V$ 

## <u>AIMEL</u>

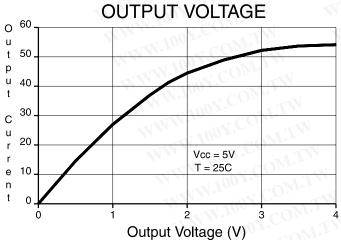
#### NORMALIZED SUPPLY CURRENT vs.



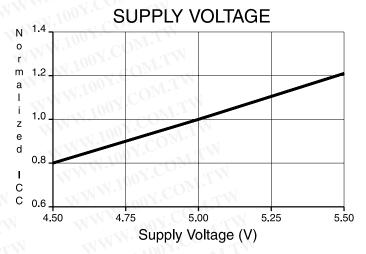
## NORMALIZED SUPPLY CURRENT vs.



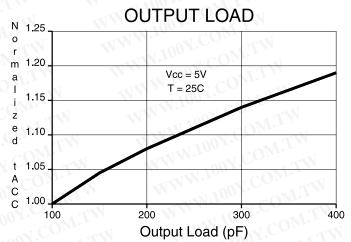
## OUTPUT SINK CURRENT vs.



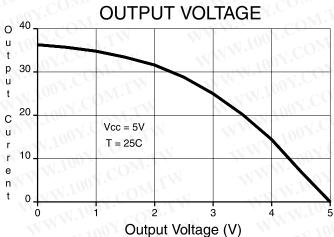
#### NORMALIZED SUPPLY CURRENT vs.



#### NORMALIZED ACCESS TIME vs.



### OUTPUT SOURCE CURRENT vs.



## AT28C64 Ordering Information

t <sub>ACC</sub> I <sub>CC</sub>		(mA)	Y.CO. TW W	W. 1007.	
(ns)	Active	Standby	Ordering Code	Package	Operation Range
120	30 TW	0.1	AT28C64-12JC AT28C64-12PC AT28C64-12SC AT28C64-12TC	32J 28P6 28S 28T	Commercial (0°C to 70°C)
.100 <sup>X</sup> .CO	45	0.1	AT28C64-12JI AT28C64-12PI AT28C64-12SI AT28C64-12TI	32J 28P6 28S 28T	Industrial (-40°C to 85°C)
150	CO 30	0.1	AT28C64-15JC AT28C64-15PC AT28C64-15SC AT28C64-15TC	32J 28P6 28S 28T	Commercial (0°C to 70°C)
WWW.1	45	0.1	AT28C64-15JI AT28C64-15PI AT28C64-15SI AT28C64-15TI	32J 28P6 28S 28T	Industrial (-40°C to 85°C)
200	30	0.1	AT28C64-20JC AT28C64-20PC AT28C64-20SC AT28C64-20TC	32J 28P6 28S 28T	Commercial (0°C to 70°C)
N	45	0.1	AT28C64-20JI AT28C64-20PI AT28C64-20SI AT28C64-20TI	32J 28P6 28S 28T	Industrial (-40°C to 85°C)
250	30	0.1	AT28C64-25JC AT28C64-25PC AT28C64-25SC AT28C64-25TC	32J 28P6 28S 28T	Commercial (0°C to 70°C)
	45	0.1	AT28C64-25JI AT28C64-25PI AT28C64-25SI AT28C64-25TI	32J 28P6 28S 28T	Industrial (-40°C to 85°C)

	Package Type	V.COM.		
32J	32-lead, Plastic J-leaded Chip Carrier (PLCC)	勝特力材料886-3-5753170		
28P6	28-lead, 0.600" Wide, Plastic Dull Inline Package (PDIP)	胜特力电子(上海) 86-21-54151736		
28S	28-lead, 0.300" Wide, Plastic Gull Wing, Small Outline (SOIC)	胜特力电子(深圳) 86-755-83298787		
28T	28-lead, Plastic Thin Small Outline Package (TSOP)	Http://www.100y.com.tw		
	Options	Trans COMT.		
Blank	Standard Device: Endurance = 10K Write Cycles; Write Time = 1 ms	N.100 3 COM. 1 TH		
E	High Endurance Option: Endurance = 100K Write Cycles; Write Tim	e = 200 µs		





#### **AT28C64X Ordering Information**

t <sub>ACC</sub>	I <sub>cc</sub>	(mA)	Kico ILM MM.	100Y.C	
(ns)	Active	Standby	Ordering Code	Package	Operation Range
(150) V.COM	30	0.1	AT28C64X-15JC AT28C64X-15PC AT28C64X-15SC AT28C64X-15TC	32J 28P6 28S 28T	Commercial (0°C to 70°C)
	45	0.1	AT28C64X-15JI AT28C64X-15PI AT28C64X-15SI AT28C64X-15TI	32J 28P6 28S 28T	Industrial (-40°C to 85°C)
200	C 30	0.1	AT28C64X-20JC AT28C64X-20PC AT28C64X-20SC AT28C64X-20TC	32J 28P6 28S 28T	Commercial (0°C to 70°C)
	45) 100 Y.CO	0.1	AT28C64X-20JI AT28C64X-20PI AT28C64X-20SI AT28C64X-20TI	32J 28P6 28S 28T	Industrial (-40°C to 85°C)
250	30	0.1	AT28C64X-25JC AT28C64X-25PC AT28C64X-25SC AT28C64X-25TC	32J 28P6 28S 28T	Commercial (0°C to 70°C)
	45	0.1 V COM	AT28C64X-25JI AT28C64X-25PI AT28C64X-25SI AT28C64X-25TI	32J 28P6 28S 28T	Industrial (-40°C to 85°C)

#### **Valid Part Numbers**

The following table lists standard Atmel products that can be ordered.

Device Numbers	Speed	Package and Temperature Combinations
AT28C64 X	12	JC, JI, PC, PI, SC, SI, TC, TI
AT28C64 X	15	JC, JI, PC, PI, SC, SI, TC, TI
AT28C64 X	20	JC, JI, PC, PI, SC, SI, TC, TI
AT28C64 X	25	JC, JI, PC, PI, SC, SI, TC, TI

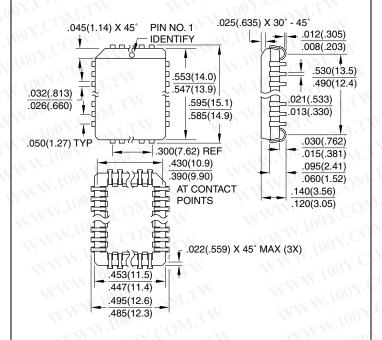
#### **Die Products**

Reference Section: Parallel EEPROM Die Products

	Package Type	VIVI 100 X
32J	32-lead, Plastic J-leaded Chip Carrier (PLCC)	WWW.100
28P6	28-lead, 0.600" Wide, Plastic Dull Inline Package (PDIP)	
28S	28-lead, 0.300" Wide, Plastic Gull Wing, Small Outline (SOIC)	1
28T	28-lead, Plastic Thin Small Outline Package (TSOP)	

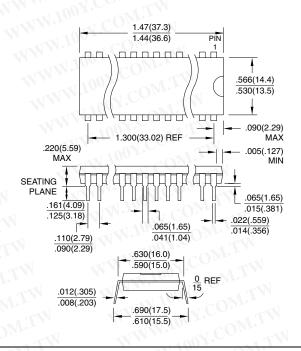
#### **Packaging Information**

**32J**, 32-lead, Plastic J-leaded Chip Carrier (PLCC) Dimensions in Inches and (Millimeters)
JEDEC STANDARD MS-016 AE



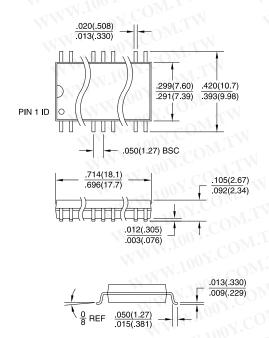
**28P6**, 28-lead, 0.600" Wide, Plastic Dual Inline Package (PDIP)
Dimensions in Inches and (Millimeters)

Dimensions in Inches and (Millimeters)
JEDEC STANDARD MS-011 AB



**28S**, 28-lead, 0.300" Wide, Plastic Gull Wing Small Outline (SOIC)

Dimensions in Inches and (Millimeters)



**28T**, 28-lead, Plastic Thin Small Outline Package (TSOP)

Dimensions in Millimeters and (Inches)\*

